

IN THE ABSTRACT:

Please DELETE the Abstract in its entirety and substitute the attached new Abstract.

An electrical component is mounted on a substrate. At least one electrical insulation film is provided to electrically insulate the component and at least section of the insulation film is connected to the component and the substrate, in such a way that the surface contours of said section of the insulation film are moulded to the surface contours formed by the component and the substrate. The insulation film has dielectric strength in relation to an electric field strength of more than 10 kV/mm and preferably more than 50 kV/mm. To produce the assembly, the insulation film is laminated onto the substrate, preferably by means of a vacuum. The component is in particular a power semiconductor component.